

BW20-12F Specification

- Version V1.0.0
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Document resume

Version	Date	Develop/revise content	Edition	Approve
V1.0.0	2024.06.13	First Edition	Xihuan Lu	Ning Guang



Content



1. Product overview

BW20-12F is a dual-band Wi-Fi + BLE SoC module developed by Ai-Thinker based on RTL8711 series chips, which supports dual-frequency (2.4 GHz or 5 GHz)802.11a/b/g/n WLAN protocol and Bluetooth 5.0 protocol. The BW 20-12F integrates dual-core MCU, a ARM V8.1 (Cortex-M4F compatible) high-performance MCU with a maximum frequency of 330 MHz; a ARM V8M (Cortex-M0 compatible) low-power MCU.

The BW20-12F module has rich peripheral interfaces, including UART / GPIO / ADC / PWM / IIC / SPI / SDIO / IR / SWD / USB etc. It can be widely used in the Internet of Things (IoT), mobile devices, wearable electronic devices, smart home and other fields.

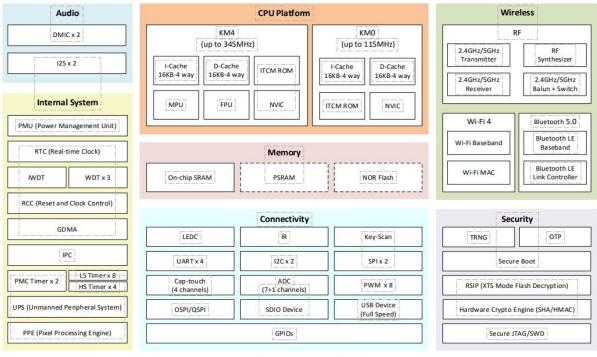


Figure 1-1 Block diagram

Figure 1 Chip Block Diagram



1.1. Characteristic

- Support for the 802.11a/b/g/n protocol
- Support for dual-frequency 2.4GHz or 5GHz
- Supports the HT20 / HT40 mode
- Support for Bluetooth 5.0
- Support for BLE Long Range
- The Bluetooth supports a high-power mode LE data length extension
- Support for link layer privacy
- Support for the hardware encryption engine Integrated dual-core MCU, up to 330 MHz
- Abundant interfaces, with 17 flexible IO ports
- Wi-Fi and Bluetooth share the same antenna
- Support secondary development, support programming in Linux and Windows environments
- Support for Arduino development



2. Main parameters

Model	BW20-12F	
Package	SMD-22	
Size 24*16*3.2(±0.2)MM		
Antenna	on-board PCB antenna、 IPEX connector (1st generation)	
Frequency range 2400~2483.5MHz or 5180~5825MHz		
Operating temperature	-40 °C~85 °C	
Storage temperature	-40 °C~125 °C, <90%RH	
Power supply	Voltage supply 3.0V~3.6V,typical value 3.3V. Current supply>500mA	
Support interface	UART/GPIO/ADC/PWM/IIC/SPI/SDIO/IR/SWD/USB	
Available IO	Default 17	
UART rate	Default 115200bps	
Bluetooth	BLE 5.0	
SPI flash	Default 4MByte,Maximum support is 16MByte	

Table 1 Description of the main parameters

2.1. Static electricity requirement

BW 20-12F module is electrostatic sensitive equipment, which requires special ESD precautions, and usually ESD protective devices should be added in use. Proper ESD handling and packaging must be used during the transportation, operation, and use of the BW 20-12F module. Do not touch the module by hand or use non-antistatic iron to damage the module.





2.2. Electrical characteristics

Table 2 Electrical characteristics table

Parameters		Condition	Min.	Typical value	Max.	Unit
Voltage supply		3V3	3.0	3.3	3.6	V
	VIL	-	-	-	0.3*VDD	V
I/O	VIH	-	0.65*VDD	-	-	V
	VOL	-	-	0.15*VDD	-	V
	VOH	-	-	0.85*VDD	-	V

2.3. Wi-Fi RF performance

Table 3 BLE RF performance

Description	Typical value			Unit	
Frequency range	2400~2483.5 and 5180~5825			MHz	
Output power					
Mode	Min. value	Typical value	Max.	Unit	
11a mode, PA output power	-	18	-	dBm	
11b mode, PA output power	-	19	-	dBm	
11g mode, PA output power	-	18	-	dBm	
11n mode, PA output power	-	17	-	dBm	
Receiving sensitivity					
Mode	Min.value	Typical value	Max.	Unit	
11b, 1Mbps	-	-99	-	dBm	
11b, 11Mbps	-	-90	-	dBm	
11a/g, 6Mbps	-	-94	-	dBm	
11a/g, 54Mbps	-	-76	-	dBm	
HT20 (MCS0)	-	-93	-	dBm	
HT20 (MCS7)	-	-74	-	dBm	
HT40 (MCS0)	-	-91	-	dBm	
HT40 (MCS7)	-	-71	-	dBm	



2.4. BLE RF performance

Table 4 BLE RF performance

Description	Typical value		Unit		
Frequency range	$2400 \sim 2484 MHz$		MHz		
	Output power				
Rate mode	Min.value	Typical value	Max.value	Unit	
1Mbps	-	15	-	dBm	
2Mbps	-	15	-	dBm	
Receiving sensitivity					
Rate mode	Min.value	Typical value	Max.value	Unit	
1Mbps @30.8%PER	-	-99	-	dBm	
2Mbps @30.8%PER	-	-97	-	dBm	



3. Appearance dimensions

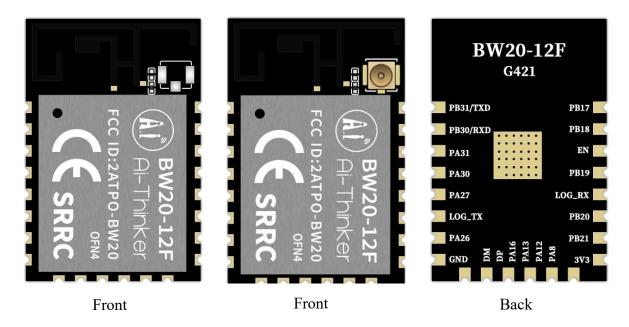
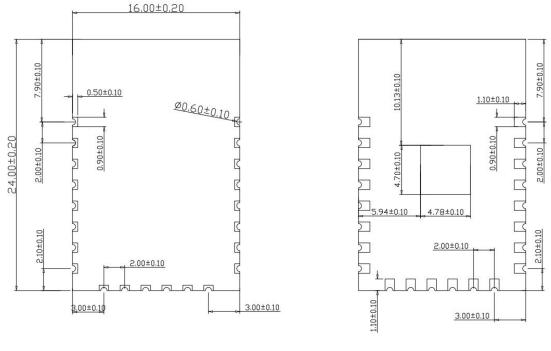


Figure 3 Appearance diagram (Rendering figure is for reference only, subject to physical objects)



Front







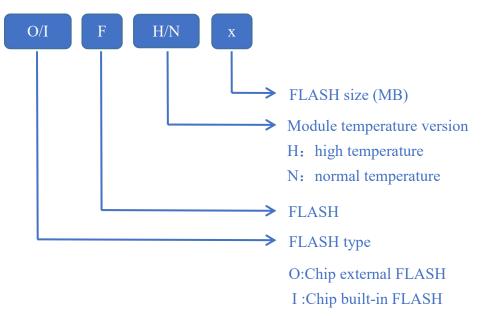


Figure 5 The screen cover information



4. Pin definition

BW20-12F is connected a total of 22 pins, as in the pin schematic diagram, and the definition of the pin function is shown in the following table.

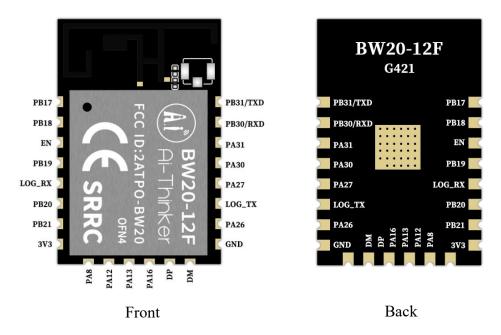


Figure 6 Pin diagram

Table 5 Pin function definition table

No.	Name	Function description	
1	PB17	TOUCH2_ADC2/SPI1_CS/SD_D3	
2	PB18	TOUCH1_ADC1/SPI1_CLK/SD_CMD	
3	EN	Chips enable pin and pull up effectively	
4	PB19	TOUCH0_ADC0/SPI1_MOSI/SD_CLK	
5	LOG_RX	UART_LOG_RXD, Firmware download RX pin	
6	PB20	SPI1_MISO/SWD_CLK/SD_D0	
7	PB21	SPI1_CS/SWD_DAT/SD_D1	
8	3V3	3.3V power supply (VDD) , the external power supply output current is recommended in above $500mA$	
9	PA8	PSRAM_DQ5/TIM8_TRIG	
10	PA12	SPI0_CS/SD_D2/TIM9_TRIG	
11	PA13	The default is not available and the IO is occupied by Flash inside the module. Please contact Ai-Thinker if need to use. SD_D2/external Flash this pin is NC	

12	PA16	The default is not available and the IO is occupied by Flash inside the module. Please contact Ai-Thinker if need to use. SPI0_MISO/SD_CLK/external Flash this pin is NC	
13	DP	PA29/SPI1_CLK/SD_CLK/FSDP	
14	DM	PA28/SPI0_MISO/SD_CMD/FSDM	
15	GND	Ground	
16	PA26	SPI0_CLK/SD_D2	
17	LOG_TX	UART LOG TXD, TX pin for download firmware, do not external pull down will enter Flash download mode	
18	PA27	SPI0_MOSI/SD_D3	
19	PA30	SPI1_MOSI/SWD_CLK/SD_D0, default function is SWD DATA, IC can be configured as PA31	
20	PA31	SPI1_MISO/SWD_DAT/SD_D1, fefault function is SWD DATA, IC can be configured as PA31	
21	PB30/RXD	UART 1 _ RXD, do not external pull down, external pull down will enter Load OTP settings	
22	PB31/TXD	UART 1 _ TXD, do not external pull down, external pull down will enter the chip test mode	

Note: 1. When LOG_TX is low level at the moment of power-on, the module enters the burning mode; when it is high level at the moment of power-on, the module starts normally and defaults is pull-up.

2. PA13 and PA16 are internally occupied in the external Flash version. At this time, these two IOs are unavailable and the pins are left floating.

3. PB30 / RXD Do not external pull down, external pull down will enter the Load OTP settings.

4. PB31 / TXD do not external down, external down will enter the chip test mode.



5. Schematic diagram

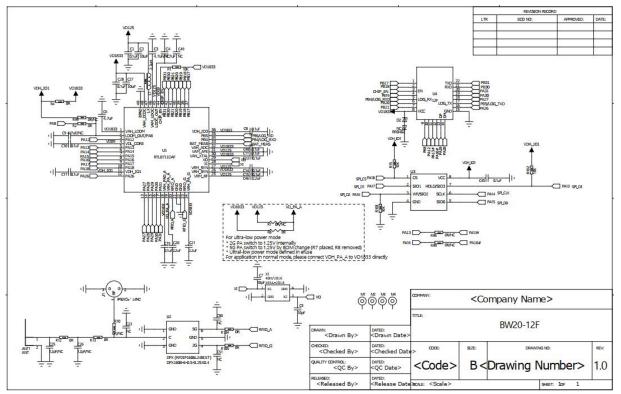


Figure 7 Schematic diagram



6. Design guide

6.1. Circuit guidance of application

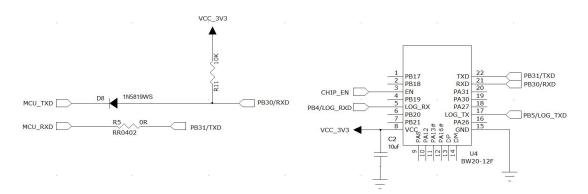


Figure 8 Circuit guidance of application

Note:

■ LOG _ TX is the starting control pin in normal operating mode at high level and burning firmware mode at low level. Internal chip default high level.

6.2. Recommend PCB package size

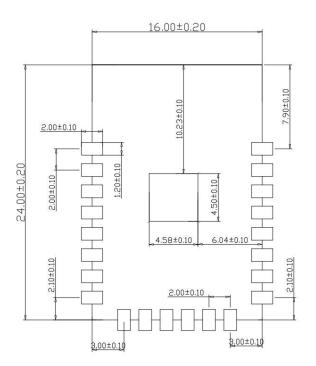


Figure 9 Recommend PCB package size (TOP view)



6.3. Antenna layout requirements

■ In the installation position on the motherboard, the following two ways are recommended:

Scheme 1: put the module on the edge of the motherboard, and the antenna area extends of the edge of the motherboard.

Scheme two: put the module on the edge of the motherboard, which hollowed an area in the antenna position.

■ In order to meet the performance of on-board antenna, metal parts are prohibited around the antenna, away from high-frequency devices.

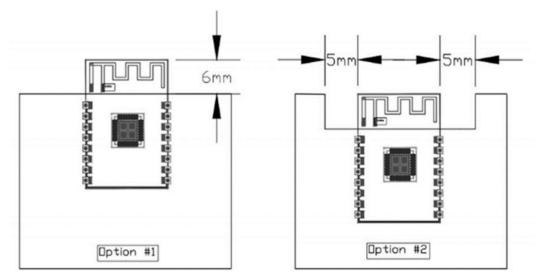


Figure 10 Schematic diagram of the antenna layout

6.4. Power supply

- Recommended 3.3V voltage, peak current above 500 mA.
- It is recommended to use LDO; if DC-DC, ripple control within 30 mV.
- The DC-DC power supply circuit suggests to reserve the position of the dynamic response capacitor, which can optimize the output ripple when the load change is large.
- 3.3V power interface, it is recommended to add ESD devices.
- If the power supply is boosted from 1.5V to 3.0V for more than 15 ms, add the voltage reset IC or use the wide voltage version Flash.
- During the repeated up and down process, if the voltage cannot be less than 0.3V, the voltage reset IC must be increased.



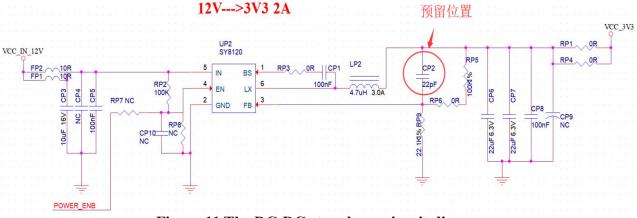


Figure 11 The DC-DC step-down circuit diagram

6.5. GPIO

- There are some IO ports on the periphery of the module. If you need to use it, it is recommended to connect a 10-100 ohm resistor in series with the IO port. This inhibits overshoot and makes both sides level more stable. It is helpful for EMI and ESD.
- For special I/O ports to be pulled up and down, refer to the usage instructions in the specifications, which may affect the module startup configuration.
- The IO port of the module is 3.3V. If the IO level of the main control and the module do not match, a level conversion circuit needs to be added.
- If the I/O port is directly connected to a peripheral port or terminals, for example, a pin row, reserve an ESD device near the terminal of the I/O cable.

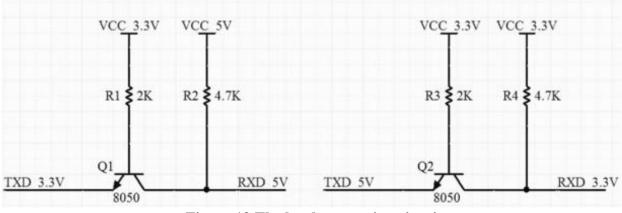


Figure 12 The level conversion circuit

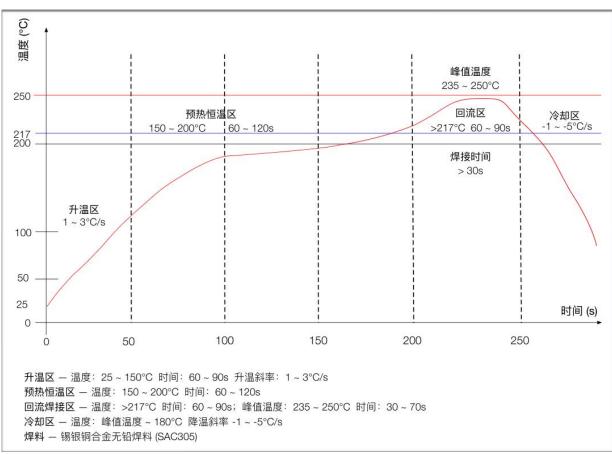


7. Storage conditions

Products sealed in moisture-proof bags should be stored in a non-condensing atmosphere of $<40 \circ C /90\%$ RH.

The module has a moisture sensitivity rating of MSL 3.

After the vacuum bag is opened, it must be used within 168 hours at $25\pm5^{\circ}C/60\%$ RH, otherwise it needs to be baked before it can be put on line again.



8. Reflow welding curve diagram

Figure 13 Reflow welding diagram



9. Product Packaging Information

BW20-12F module module was packaged in a tape, 800pcs/reel.As shown in the below image:



Figure 14 Package and packing diagram

10.Contact us

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